

## **MAX2691**

## **L2 Band GPS Low-Noise Amplifier**

### **General Description**

The MAX2691 low-noise amplifier (LNA) is designed for GPS L2 applications. Designed in Maxim's advanced SiGe process, the device achieves high gain and low noise figure while maximizing the input-referred 1dB compression point and the 3rd-order intercept point. The MAX2691 provides a high gain of 17.5dB and sub 1dB noise figure.

The device operates from a +1.6V to +3.6V single supply. The optional shutdown feature in the device reduces the typical supply current to 4µA. The device is available in a very small, lead-free, RoHS-compliant, 0.86mm x 0.86mm x 0.65mm wafer-level package (WLP).

### **Applications**

Precision Navigation

Telematics (Asset Tracking and Management) **Avionics** 

#### **Features**

♦ High-Power Gain: 17.5dB

♦ Low-Noise Figure: 0.93dB

♦ Integrated 50Ω Output Matching Circuit

♦ Low Supply Current: 4.3mA

♦ Wide Supply Voltage Range: 1.6V to 3.6V

♦ Low Bill of Materials: One Inductor, Two

**Capacitors** 

♦ Small Footprint: 0.86mm x 0.86mm

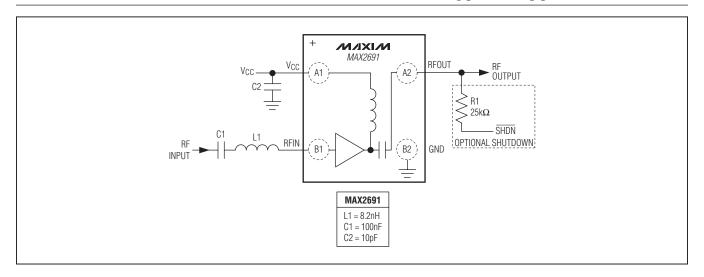
♦ Thin Profile: 0.65mm

♦ 0.4mm-Pitch Wafer-Level Package (WLP)

Ordering Information appears at end of data sheet.

For related parts and recommended products to use with this part, refer to www.maxim-ic.com/MAX2691.related.

### Typical Application Circuit



#### **ABSOLUTE MAXIMUM RATINGS**

V <sub>CC</sub> to GND0.3V to +3.6V	Operating Temperature Range40°C to +85°C
Other Pins to GND	Junction Temperature+150°C
(except RFIN)0.3V to (+ Operating V <sub>CC</sub> + 0.3V)	Storage Temperature Range65°C to +160°C
Maximum Current into RF Input10mA	Lead Temperature (soldering, 10s) Reflow Profile (Note 1)
Maximum RF Input Power+5dBm	Soldering Temperature (reflow)+260°C
Continuous Power Dissipation ( $T_A = +70^{\circ}C$ )	
4-Bump WLP (derates 9.7mW/°C above +70°C)776mW	

Note 1: Refer to Application Note 1891: Wafer-Level Packaging (WLP) and Its Applications.



Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

### DC ELECTRICAL CHARACTERISTICS

(MAX2691 EV kit,  $V_{CC}$  = 1.6V to 3.6V,  $T_A$  = -40°C to +85°C, no RF signals are applied. Typical values are at  $V_{CC}$  = 2.85V and  $T_A = +25$ °C, unless otherwise noted.) (Note 2)

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
Supply Voltage		1.6	2.85	3.6	V
Supply Current	SHDN = high		4.3		mA
	Shutdown mode, SHDN = low		4.0	20	μΑ
Digital Input Logic-High	(Note 3)	1.2			V
Digital Input Logic-Low	(Note 3)			0.45	V

### **AC ELECTRICAL CHARACTERISTICS**

(MAX2691 EV kit,  $V_{CC}$  = 1.6V to 3.6V,  $T_A$  = -40°C to +85°C,  $f_{RFIN}$  = 1227MHz. Typical values are at  $V_{CC}$  = 2.85V and  $T_A$  = +25°C, unless otherwise noted.) (Note 2)

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS	
RF Frequency	L2 band		1227		MHz	
Dower Cain (Note 4)	V <sub>CC</sub> = 2.85V	13.3	13.3 17.5		-10	
Power Gain (Note 4)	$V_{CC} = 1.6V$	13.1	17.4		dB	
Noise Figure	V <sub>CC</sub> = 1.6V to 3.3V		0.93		dB	
In-Band 3rd-Order Input Intercept Point	(Note 5)		-3.0		dBm	
Input 1dB Compression Point	(Note 6)		-8.5		dBm	
Input Return Loss			10.9		dB	

### AC ELECTRICAL CHARACTERISTICS (continued)

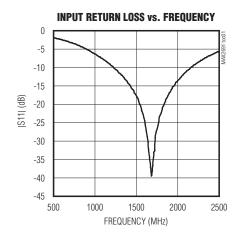
(MAX2691 EV kit,  $V_{CC} = 1.6V$  to 3.6V,  $T_A = -40^{\circ}$ C to  $+85^{\circ}$ C,  $f_{RFIN} = 1227$ MHz. Typical values are at  $V_{CC} = 2.85V$  and  $T_A = +25^{\circ}$ C, unless otherwise noted.) (Note 2)

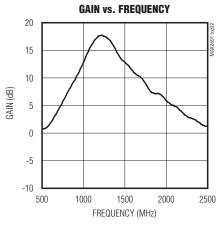
PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
Output Return Loss			15.6		dB
Reverse Isolation			45		dB

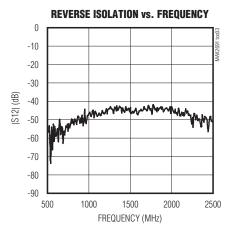
- Note 2: Min and max limits guaranteed by test at  $T_A = +25^{\circ}C$  and guaranteed by design and characterization at  $T_A = -40^{\circ}C$  and  $T_A = +85$ °C, unless otherwise noted.
- **Note 3:** Min and max limits guaranteed by test at  $T_A = +25$ °C.
- Note 4: Min limit guaranteed by design and characterization.
- Note 5: Measured with the two tones located at 1MHz and 2MHz offset from the center of the GPS band with -30dBm/tone.
- Note 6: Measured with a tone located at 5MHz offset from the center of the GPS band.

### **Typical Operating Characteristics**

(MAX2691 EV kit. Typical values are at  $V_{CC} = 2.85V$ ,  $T_A = +25^{\circ}C$ , and  $f_{RFIN} = 1227MHz$ , unless otherwise noted.)

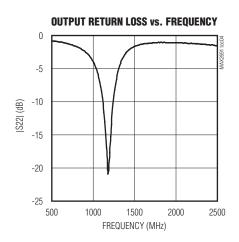


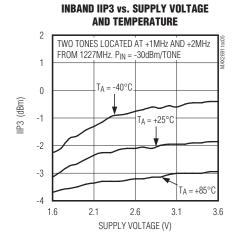


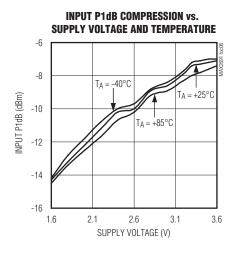


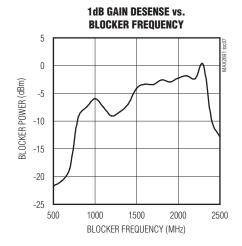
## **Typical Operating Characteristics (continued)**

(MAX2691 EV kit. Typical values are at  $V_{CC}$  = 2.85V,  $T_A$  = +25°C, and  $f_{RFIN}$  = 1227MHz, unless otherwise noted.)

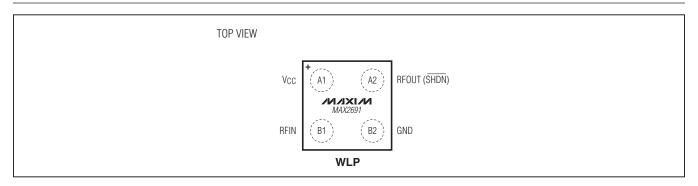








### **Bump Configuration**



### **Bump Description**

BUMP NAME FUNCTION		FUNCTION
A1	V <sub>CC</sub>	Supply Voltage. Bypass to ground with a 10pF capacitor as close as possible to the IC.
A2	RFOUT (SHDN)	RF Output/SHDN Input. RFOUT is internally matched to $50\Omega$ and pulled up to $V_{CC}$ through a $1M\Omega$ resistor. SHDN is shared with the RFOUT bump. The device is in active mode by default once $V_{CC}$ is applied. RFOUT(SHDN) can be pulled to a DC low through a $25k\Omega$ resistor to shut down the IC.
B1	RFIN	RF Input. Requires a DC-blocking capacitor and external matching components.
B2	GND	Ground. Connect to the PCB ground plane.

## **Detailed Description**

The MAX2691 LNA is designed for GPS L2 applications. The device features a power-shutdown control mode to eliminate the need for an external supply switch. The device achieves high gain, low noise figure, and excellent linearity.

#### **Input and Output Matching**

The MAX2691 requires an off-chip input match. Only an inductor in series with a DC-blocking capacitor is needed to form the input matching circuit. The Typical Application *Circuit* shows the recommended input-matching network. These values are optimized for the best simultaneous gain, noise figure, and return loss performance. Reducing the input coupling capacitor results in a lower IIP3. The device integrates an on-chip output matching to  $50\Omega$  at the output, eliminating the need for external matching components. Table 1 lists typical device S parameters and K<sub>f</sub> values. Typical noise parameters are shown in Table 2.

#### Shutdown

The MAX2691 includes an optional shutdown feature to turn off the entire chip. The device is placed in active mode by default once V<sub>CC</sub> is applied, due to the on-chip pullup resistor to VCC at the RFOUT bump (shared with the SHDN input). To shut down the part, apply a logic-low to the RFOUT bump through an external resistor with an adequate value, e.g.,  $25k\Omega$ , in order not to load the RF output signal during active operation.

## **Applications Information**

A properly designed PCB is essential to any RF microwave circuit. Use controlled-impedance lines on all high-frequency inputs and outputs. Bypass V<sub>CC</sub> with decoupling capacitors located close to the device. For long V<sub>CC</sub> lines, it may be necessary to add decoupling capacitors. Locate these additional capacitors further away from the device package. Proper grounding of the GND pin is essential. If the PCB uses a topside RF ground, connect it directly to the GND pin. For a board where the ground is not on the component layer, connect the GND pin to the board with multiple vias close to the package.

Refer to www.maxim-ic.com for the MAX2691 EV kit schematic, Gerber data, PADS layout file, and BOM information.

Table 1. Typical S Parameter Values and K-Factor

FREQ. (MHz)	S11 MAG (dB)	S11 PHASE (DEGREES)	S21 MAG (dB)	S21 PHASE (DEGREES)	S12 MAG (dB)	S12 PHASE (DEGREES)	S22 MAG (dB)	S22 PHASE (DEGREES)	K <sub>f</sub>
700	-2.1	-78.1	3.5	-175.7	-54.0	113.3	-1.3	-124.9	16.75126
800	-2.5	-87.1	6.0	175.7	-47.7	112.0	-1.6	-143.3	8.847551
900	-2.8	-96.2	8.8	163.0	-55.5	85.4	-2.4	-162.8	22.33037
1000	-3.1	-104.3	11.7	146.2	-53.8	54.0	-3.9	175.0	19.54059
1100	-3.4	-112.3	14.4	119.2	-46.3	33.8	-8.3	149.5	9.366309
1200	-3.7	-119.4	16.0	83.5	-46.9	15.3	-19.1	-126.9	9.788318
1220	-3.7	-120.7	16.1	75.6	-47.6	-1.0	-14.2	-114.7	10.25069
1240	-3.7	-122.4	16.0	67.9	-49.4	20.3	-10.9	-114.4	12.09861
1260	-3.8	-123.7	15.9	60.1	-49.7	14.9	-8.7	-118.5	12.1323
1280	-3.8	-125.0	15.6	52.8	-47.3	-6.0	-6.9	-124.3	8.793041
1300	-3.8	-126.6	15.2	46.0	-43.5	19.6	-5.7	-130.2	5.277003
1400	-4.0	-133.5	13.4	18.4	-44.9	-22.8	-2.6	-157.6	4.94144
1500	-4.1	-140.3	11.3	-0.5	-48.5	-21.4	-1.6	-179.3	6.656188
1600	-4.1	-147.6	9.4	-15.6	-47.7	-23.6	-1.3	163.8	5.983826
1700	-4.1	-154.6	7.8	-28.5	-44.8	-16.5	-1.0	148.8	4.18904

Table 2. Typical Noise Parameters ( $V_{CC} = 2.85V$ ,  $T_A = +25^{\circ}C$ )

			•	
FREQUENCY (MHz)	FMIN (dB)	I □ OPT I	IFOPTI ANGLE	R <sub>N</sub> (I)
1200	0.66	0.45	47	8.37
1210	0.66	0.45	48	8.35
1220	0.66	0.45	48	8.33
1230	0.66	0.45	48	8.30
1240	0.66	0.45	49	8.28
1250	0.66	0.45	49	8.26
1260	0.66	0.45	50	8.24
1270	0.67	0.45	50	8.22
1280	0.67	0.44	50	8.20
1290	0.67	0.44	51	8.18
1300	0.67	0.44	51	8.17

## **Ordering Information**

PART	TEMP RANGE	PIN-PACKAGE
MAX2691EWS+T	-40°C to +85°C	4 WLP

<sup>+</sup>Denotes a lead(Pb)-free/RoHS-compliant package. T = Tape and reel.

#### **Chip Information**

PROCESS: SiGe BiCMOS

### **Package Information**

For the latest package outline information and land patterns (footprints), go to www.maxim-ic.com/packages. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

PACKAGE	PACKAGE	OUTLINE	LAND
TYPE	CODE	NO.	PATTERN NO.
4 WLP	W40A0+1	<u>21-0480</u>	